

Product / Process Change Notification CYAR-7S9PQC[Home](#)

The information below reflects a change that is being implemented.

Notice Date: 11/20/2009
Product Category: 24xxx
Notification Subject: CCB #759-5: Conversion of 24xx512 product families to 160K TLM

Notification Body:
PCN Status:
Final notification

Microchip Parts Affected:
24AA512, 24LC512, and 24FC512 serial EEPROM families.

Description of Change:
The serial EEPROMs listed will be moved from their current 160K double layer metal (DLM), (0.4 micron) fabrication process to the 160K triple layer metal (TLM), (0.4 micron) process. In order to continue receiving devices from the 160K DLM process, the 'Revised 160K DLM Part Numbers' (RVE) listed below must be used. If an order is received using the Current Part Number, Microchip will ship either the new device from the 160K TLM process or the current device from the 160K DLM process until this inventory is depleted. The devices affected include all voltages, temperatures, and packages of the listed part numbers.

Current Standard Part Number / Revised Standard 160K DLM Part Number
24LC512-x/xx / 24LC512-x/xxRVE
24AA512-x/xx / 24AA512-x/xxRVE
24FC512-x/xx / 24FC512-x/xxRVE

Note: Die and Vxx (automotive) parts are not affected.

Impacts to Data Sheet:
Endurance specified as page mode. See Section 6 of product data sheet DS21754 which states: "When doing a write of less than 256 bytes the data in the rest of the page is refreshed along with the data bytes being written. For this reason, endurance is specified per page."

Reason for Change:
To improve manufacturability and to add the 8-lead TSSOP and 8-lead 150 mil SOIC packages.

Change Implementation Status:
In progress

Estimated First Ship Date(s):
December 20, 2009 (0952)

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)
Traceability codes

Close